Ref #	Hits	Search Query	DBs	Default Operato r	Plural s	Time Stamp
L1	6395	(dic\$3 near5 (tape film substrate))	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/01 18:27
.2	5420	1 and (trench groove recess via open\$3)	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/01 18:28
_3	3600	2 and (insulat\$3 encapsulat\$3)	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/01 18:28
.5	3600	3 and ((insulat\$3 encapsulat\$3) nea100 (dic\$3 near5 (tape film substrate)))	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/01 18:06
.6	204	5 and stretch\$3	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/01 18:07
.7	2900	(dic\$3 near5 (tape film substrate))	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/04/01 18:27
L8	671	7 and (trench groove recess via open\$3)	EPO; JPO; DERWENT	OR	ON	2005/04/01 18:28
L9	141	8 and (insulat\$3	IBM_TDB EPO; JPO;	OR	ON	2005/04/01
		encapsulat\$3)	DERWENT; IBM_TDB			18:28

Ref #	Hits	Search Query	DBs	Default Operato r	Plural s	Time Stamp
L21	666	(mold\$3 same encapsulat\$3 same (barrier protect\$3) same (peel\$3 remov\$3))	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/01 20:48
L22	190	(mold\$3 same encapsulat\$3 same (barrier protect\$3) same (peel\$3 remov\$3) same (groove recess open\$3 trench\$3))	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/01 20:50
L23	282	((mold\$3 resin) same encapsulat\$3 same (barrier protect\$3) same (peel\$3 remov\$3) same (groove recess open\$3 trench\$3))	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/01 20:50
L24	282	22 23	US-PGPU B; USPAT; USOCR	OR	ON	2005/04/01 20:51